

AMENDMENTS TO THE SPECIFICATION

Please amend paragraph [0017] of the published application as follows:

--FIGS. 4(a)-4(l) ~~[[4(j)]]~~ show a method of preparing a wafer in accordance with the invention. --.

Please amend paragraph [0032] of the published application as follows:

--In accordance with another aspect of the invention and as depicted in FIGS. 4(a)- 4(l) ~~[[4(j)]]~~ the invention provides a method of producing a wafer. This method can be used to produced an SOI or SOQ-type wafer 7 and 15 such as those depicted in FIGS. 1 and 2, wherein the back surface 3 of the wafer is covered by the cap layer 4, although the method of the invention is not so limited. While a number of processes are known in the art to obtain SOI or SOQ-type wafers, as depicted herein, the well known SMARTCUT® process is shown, as modified by the invention disclosed herein. Specifically, of interest are the process steps providing the cap layer 4 on the back surface 3 of the wafer.--.